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Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC/IEEE 8802-3

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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INDUSTRIAL COMMUNICATION NETWORKS – PROFILES –

Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC/IEEE 8802-3

FOREWORD

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NOTE Combinations of protocol types are specified in IEC 61784-1 and IEC 61784-2.

International Standard IEC 61784-2 has been prepared by subcommittee 65C: Industrial networks, of IEC technical committee 65: Industrial-process measurement, control and automation.

This fourth edition cancels and replaces the third edition published in 2014. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- update of reference from ISO/IEC 8802-3 to ISO/IEC/IEEE 8802-3;
- update of the dated references to the IEC 61158 series, to IEC 61784-1, to the IEC 61784-5 series and to IEC 61918 throughout the document;

- update of selection tables for CPF 2, CPF 3, CPF 4, CPF 8 and CPF 17;
- CPF3: update of the requirements for all conformance classes;
- CPF3: updated timing requirements for IO devices;
- CPF3: refining the added application classes;
- addition of a new Communication Profile Family – CPF 20 in Clause 21;
- addition of a new Communication Profile Family – CPF 21 in Clause 22.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65c/943/FDIS	65c/952/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61784 series, published under the general title *Industrial communication networks – Profiles*, can be found on the IEC web site.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

This document provides additional Communication Profiles (CP) to the existing Communication Profile Families (CPF) of IEC 61784-1 and additional CPFs with one or more CPs. These profiles meet the industrial automation market objective of identifying Real-Time Ethernet (RTE) communication networks coexisting with ISO/IEC/IEEE 8802-3 – commonly known as Ethernet. These RTE communication networks use provision from ISO/IEC/IEEE 8802-3 for the lower communication stack layers and additionally provide more predictable and reliable real-time data transfer and means for support of precise synchronization of automation equipment.

More specifically, these profiles help to correctly state the compliance of RTE communication networks with ISO/IEC/IEEE 8802-3, and to avoid the spreading of divergent implementations.

Adoption of Ethernet technology for industrial communication between controllers and even for communication with field devices promotes use of Internet technologies in the field area. This availability would be unacceptable if it causes the loss of features required in the field area for industrial communication automation networks, such as:

- real-time,
- synchronized actions between field devices like drives,
- efficient, frequent exchange of very small data records.

These new RTE profiles may take advantage of the improvements of Ethernet networks in terms of transmission bandwidth and network span.

Another implicit but essential requirement is that the typical Ethernet communication capabilities, as used in the office world, are fully retained, so that the software involved remains applicable.

The market is in need of several network solutions, each with different performance characteristics and functional capabilities, matching the diverse application requirements. RTE performance indicators (see Clause 5), which values will be provided with RTE devices based on communication profiles specified in this document, enable the user to match network devices with application-dependent performance requirements of an RTE network.

Subclause 5.1 specifies basic principles of performance indicators required to express RTE performance of a CP. Subclause 5.2 describes the view of application requirements. An application-dependent class could be used to find out a suitable CP. Clause 4 specifies how conformance of a device to the CPF or CP should be stated.

INDUSTRIAL COMMUNICATION NETWORKS – PROFILES –

Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC/IEEE 8802-3

1 Scope

This part of IEC 61784 specifies

- performance indicators supporting classification schemes for Real-Time Ethernet (RTE) requirements;
- profiles and related network components based on ISO/IEC/IEEE 8802-3, IEC 61158 series, and IEC 61784-1;
- RTE solutions that are able to run in parallel with ISO/IEC/IEEE 8802-3 based applications.

These communication profiles are called Real-Time Ethernet communication profiles.

NOTE The RTE communication profiles use ISO/IEC/IEEE 8802-3 communication networks and its related network components or IEC 61588 and may in some cases amend those standards to obtain RTE features.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE All parts of the IEC 61158 series, as well as IEC 61784-1 and IEC 61784-2 are maintained simultaneously. Cross-references to these documents within the text therefore refer to the editions as dated in this list of normative references.

IEC 61158 (all parts), *Industrial communication networks – Fieldbus specifications*

IEC 61158-1:201X, *Industrial communication networks – Fieldbus specifications – Part 1: Overview and guidance for the IEC 61158 and IEC 61784 series*

IEC 61158-2:2014, *Industrial communication networks – Fieldbus specifications – Part 2: Physical layer specification and service definition*

IEC 61158-3-2:2014, *Industrial communication networks – Fieldbus specifications – Part 3-2: Data-link layer service definition – Type 2 elements*
IEC 61158-3-2:2014/AMD1:201X

IEC 61158-3-4:201X, *Industrial communication networks – Fieldbus specifications – Part 3-4: Data-link layer service definition – Type 4 elements*

IEC 61158-3-11:2007, *Industrial communication networks – Fieldbus specifications – Part 3-11: Data-link layer service definition – Type 11 elements*

IEC 61158-3-12:201X, *Industrial communication networks – Fieldbus specifications – Part 3-12: Data-link layer service definition – Type 12 elements*